

Product Change Notification - ASER-28LQKG396

Date:

20 Nov 2019

Product Category:

Others; Computing Embedded Controllers; Ethernet Switches; USB Bridge

Affected CPNs:



Notification subject:

CCB 3870 Final Notice: Qualification of MMT as an additional assembly site for selected SMSC KBC1126, SCH555X, MEC1310, LAN931X and USB22XX device families available in 128L TQFP (14x14x1mm) package.

Notification text:

PCN Status:

Final notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open one of the icons found in the Affected CPNs section above.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of MMT as an additional assembly site for selected SMSC KBC1126, SCH555X, MEC1310, LAN931X and USB22XX device families available in 128L TQFP (14x14x1mm) package.

Pre Change:

Assembled at ASE assembly site using Au/PdCu wire material, 1076WA die attach, and G631H molding compound material.

Post Change:

Assembled at ASE assembly site using Au/PdCu wire, 1076WA die attach, and G631H molding compound material or assembled at MMT assembly site using CuPdAu wire, 3280 die attach, and G700HA molding compound.

Pre and Post Change Summary:

	Pre Change	Post C	hange
Assembly Site	Advanced Semiconductor Engineering, Inc. (ASE)	Advanced Semiconductor Engineering, Inc. (ASE)	Microchip Technology Thailand (Branch) (MMT)
Wire material	Au/PdCu	Au/PdCu	CuPdAu
Die attach material	1076WA	1076WA	3280
Molding compound material	G631H	G631H	G700HA



Lead frame	C7025	C7025	C7025
material	C7025		C7025

Impacts to Data Sheet:

None.

Change Impact:

None.

Reason for Change:

To improve manufacturability by qualifying MMT as an additional assembly site.

Change Implementation Status:

Complete

Estimated First Ship Date:

December 20, 2019 (date code: 1952)

Time Table Summary:

		July 2019		>	November 2019				December 2019							
Workweek	27	28	29	30	31	>	44	45	46	47	48	49	50	51	52	1
Initial PCN Issue																
Date		Х														
Qual Report										V						
Availability										^						
Final PCN Issue Date										Χ						
Estimated														V		
Implementation Date														^		

Method to Identify Change:

Traceability code

Qualification Report:

Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Revision History:

July 09, 2019: Issued initial notification.

November 20, 2019: Issued final notification. Attached the qualification report. Revised the affected parts list. Provided estimated first ship date to be on December 20, 2019.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachment(s):

PCN ASER-28LQKG396 Qual Report.pdf

Please contact your local <u>Microchip sales office</u> with questions or concerns regarding this notification.



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Affected Catalog Part Numbers (CPN)

KBC1126-NU

SCH5555-NU

SCH5553-NU

SCH5555V-NU

SCH5555-NU-TR

SCH5553-NU-TR

MEC1310-NU

MEC1310-NU-TR

LAN9311-NU

LAN9313-NU

LAN9313-NU-TR

USB2227-NU-11

USB2228-NU-11

USB2250-NU-06

USB2251-NU-06

USB2250I-NU-06

USB2251I-NU-06

USB2251I-NU-06-CAG